

Final Product/Process Change Notification Document #:FPCN23971XE Issue Date:01 Nov 2022

| Title of Change:                             | Transfer of FS50 wafer technology from Macronix (MXIC) Taiwan to onsemi South Portland Maine FAB  |                              |  |  |
|--|---|------------------------------|--|--|
| Proposed First Ship date:                    | 06 Feb 2023 or earlier if approved by customer  |                              |  |  |
| Contact Information:                         | Contact your local onsemi Sales Office or SangSeop.Kim@onsemi.com   |                              |  |  |
| PCN Samples Contact:                         | Contact your local onsemi Sales Office.<br>Sample requests are to be submitted no later than 30 days from the date of first notification,<br>Initial PCN or Final PCN, for this change.<br>Samples delivery timing will be subject to request date, sample quantity and special customer<br>packing/label requirements. |                              |  |  |
| Additional Reliability Data:                 | Contact your local onsemi Sales Office or Dongsun.Park@onsemi.com   |                              |  |  |
| Type of Notification:                        | This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com       |                              |  |  |
| Marking of Parts/ Traceability of<br>Change: | As material from different FABs cannot be combined in to (1) box, Affected parts will be identified by lot # and date code<br>Please see sample MPN on page 3 at the following link<br>http://www.onsemi.com/pub_link/Collateral/LABELRM-D.PDF to see the location of the Diffused In notation.                         |                              |  |  |
| Change Category:                             | Wafer Fab Change  |                              |  |  |
| Change Sub-Category(s):                      | Manufacturing Site Addition   |                              |  |  |
| Sites Affected:                              |   |                              |  |  |
| onsemi Sites                                 | External Found  | dry/Subcon Sites             |  |  |
| onsemi Bucheon, Korea                        | Diodes, Maine, I  | Diodes, Maine, United States |  |  |

#### Description and Purpose:

onsemi would like to inform out customers of the qualification of our FS50 Technology into the 8" Diodes, Maine, US FAB Foundry, and OLDFET MOSFET into onsemi Bunchon, Korea. This technology was processed out of our 6" foundry Macronix (MXIC) in Taiwan and 8" foundry Towerjazz Semiconductor in Japan. MXIC and Towerjazz announced it will discontinue this technology, thus necessitating the transfer.

While the typical language of the FPCN is to wait 90 days until shipments of first material, as there is no inventory of MXIC wafer, die, assembly WIP or finished goods either at onsemi or at our distributors, there will be no waiting period for approval or rejection of the PCN and deliveries will start immediately. If a customer does not wish to receive product from the new wafer FAB, they should take action to cancel or push out all future orders. onsemi can no longer provide material from the original MXIC FAB site. Customers should work with their local sales contacts to cancel or push orders as needed.

|          |            | From                                   | То                    |
|----------|------------|--|-----------------------|
| FAB Site |            | Macronix (MXIC) Taiwan                 | Diodes, Maine, US     |
| IC       | Wafer Size | 6″                                     | 8"                    |
|          | FAB Site   | Towerjazz Semiconductor, Japan(Toyama) | onsemi Bucheon, Korea |
| MosFET   | Wafer Size | 8″                                     | 6″                    |

There are no product material changes as a result of this change

There is no product marking change as a result of this change

# onsemi

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#### **Reliability Data Summary:**

QV DEVICE NAME: FL7733AMX RMS: K72044, O80421, O81140 PACKAGE: SOIC8

| Test  | Specification       | Condition   | Interval | Results |
|-------|---------------------|---|----------|---------|
| HTOL  | JESD22-A108         | Ta=125°C, 100 % max rated Vcc                                   | 1008 hrs | 0/231   |
| HTSL  | JESD22-A103         | Ta= 150°C   | 1008 hrs | 0/231   |
| PC    | J-STD-020 JESD-A113 | MSL 1 @ 260 °C, Pre TC, uHAST, HAST for surface mount pkgs only |          | Pass    |
| TC    | JESD22-A104         | Ta= -55°C to +150°C   | 1000 сус | 0/231   |
| HAST  | JESD22-A110         | 130°C, 85% RH, 33.3psig, bias                                   | 96 hrs   | 0/231   |
| uHAST | JESD22-A118         | 130°C, 85% RH, 18.8psig, unbiased 96                            |          | 0/231   |

## QV DEVICE NAME: GF001HN RMS: K84873 PACKAGE: PDIP8

| ٦ | Test | Specification | Condition                      | Interval | Results |
|---|------|---------------|--------------------------------|----------|---------|
| Н | ITOL | JESD22-A108   | Ta=125°C, 100 % max rated Vcc, | 1008 hrs | 0/77    |

QV DEVICE NAME: FSQ0270RNA RMS: K84036, K84039 PACKAGE: PDIP8

| Test  | Specification       | Condition   | Interval | Results |
|-------|---------------------|---|----------|---------|
| HTSL  | JESD22-A103         | Ta= 150°C   | 1008 hrs | 0/231   |
| PC    | J-STD-020 JESD-A113 | MSL 1 @ 260 °C, Pre TC, uHAST, HAST for surface mount pkgs only |          | Pass    |
| TC    | JESD22-A104         | Ta= -55°C to +150°C   | 1000 cyc | 0/231   |
| HAST  | JESD22-A110         | 130°C, 85% RH, 33.3psig, bias                                   | 96 hrs   | 0/231   |
| uHAST | JESD22-A118         | 130°C, 85% RH, 18.8psig, unbiased                               | 96 hrs   | 0/231   |

### **Electrical Characteristics Summary:**

Electrical characteristics impact: specification limit change

|         | From      | То          |
|---------|-----------|-------------|
| IDD_OLP | 30 ~ 90uA | 40 ~ 100uA  |
| IHV     | 1.5 ~ 5mA | 1.2 ~ 4.7mA |



#### List of Affected Parts:

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

| Part Number | Qualification Vehicle          |  |
|-------------|--------------------------------|--|
| GF001HN     | FL7733AMX, GF001HN, FSQ0270RNA |  |

# Appendix A: Changed Products

# DIKG: DIGI-KEY

| Product | Customer Part Number | Qualification Vehicle | New Part Number | Replacement Supplier |
|---------|----------------------|-----------------------|-----------------|----------------------|
| GF001HN |                      | FL7733AMX,            |                 |                      |
|         |                      | GF001HN,              |                 |                      |
|         |                      | FSQ0270RNA            |                 |                      |